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**FOR IMMEDIATE RELEASE**

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**Samtec Launches 800-Position AcceleRate® HP**

**High-Performance Array Connectors**

*AcceleRate® HP high-performance array connectors feature 112 Gbps PAM4 performance, a flexible open pin field design, and a highly reliable Solder Column Termination.*

**New Albany, IN:** Samtec, Inc., a global leader in high-performance interconnect solutions and a service leader in the industry, announces the expansion of its AcceleRate® HP product line with the release of 800-position APM6 and APF6 high-performance array connectors available in a low-profile 5mm stack height.

Several black rectangular objects with gold colored wires

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Engineered for next-generation demands, the new AcceleRate® HP connectors deliver exceptional signal integrity and density, supporting data rates up to 112 Gbps PAM4 on a 0.635mm pitch. These connectors are optimized for high-throughput applications such as High-Performance Computing (HPC), Artificial Intelligence (AI), storage, and networking.

Key features include:

* Protocol compatibility with PCIe® 6.0, CXL® 3.2, and 100 GbE
* 800-position configuration (8 rows × 100 positions) in a dense footprint of 68.62mm × 18.20mm (2.701” × 0.717”)
* 5mm mated stack height, with a 10mm version planned for Q2 2026
* 92.5 Ohm impedance
* 1.2 A max current rating (one pin powered per row), and 150 VAC (212 VDC) max voltage rating
* Open pin field array design for maximum grounding and routing flexibility

The APM6 and APF6 connectors utilize Samtec’s Solder Column Termination, enhancing structural integrity. This IPC Class 3 compliant method is ideal for dense, high-speed interconnects and offers superior solder joint reliability and excellent insertion loss and return loss performance.

“These new 800-position connectors represent a significant advancement in high-density, high-speed interconnect technology,” said Eric Mings, Samtec’s High-Speed Board-to-Board Product Manager. “They’re designed to meet the rigorous demands of today’s data-intensive systems while maintaining reliability.”

Samtec’s APM6 and APF6 products are available directly through Samtec or through authorized distribution partners. For more information, visit [samtec.com/accelerateHP](https://www.samtec.com/high-speed-board-to-board/high-density-arrays/accelerate-hp/) or contact the High-Speed Board-to-Board Group at [HSB2B@samtec.com](mailto:HSB2B@samtec.com).

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**About Samtec, Inc.**

Founded in 1976, Samtec is a privately held, $1 Billion global manufacturer of a broad line of electronic interconnect solutions, including High-Speed Board-to-Board, High-Speed Cables, Mid-Board and Panel Optics, Precision RF, Flexible Stacking, and Micro/Rugged components and cables. Samtec Technology Centers are dedicated to developing and advancing technologies, strategies, and products to optimize both the performance and cost of a system from the bare die to an interface 100 meters away, and all interconnect points in between. With 40+ international locations and products sold in more than 125 different countries, Samtec’s global presence enables its unmatched customer service. For more information, please visit: <http://www.samtec.com>.

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